

N-Channel Super Junction Power MOSFET IV

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

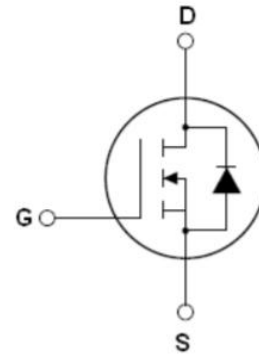
Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

$V_{DS\ min@T_{jmax}}$	550	V
$R_{DS(ON)TYP.}$	470	m Ω
I_D	7.5	A
Q_g	13.3	nC



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE50N540F	TO-220F	NCE50N540F



TO-220F

Table 1. Absolute Maximum Ratings ($T_J=25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	500	V
Gate-Source Voltage ($V_{DS}=0V$), AC ($f>1\text{ Hz}$)	V_{GS}	± 30	V
Gate-Source Voltage ($V_{DS}=0V$), DC	V_{GS}	± 20	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_{D(DC)}$	7.5	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_{D(DC)}$	5.25	A
Pulsed drain current (Note 1)	$I_{DM(pulse)}$	22.5	A
Maximum Power Dissipation($T_c=25^\circ\text{C}$)	P_D	30.9	W
Derate above 25°C		0.20	W/ $^\circ\text{C}$
Single pulse avalanche current (Note 2)	I_{AS}	2	A
Reverse diode dv/dt , $V_{DS} \leq 480\text{ V}$, $I_{SD}<I_D$	dv/dt	15	V/ns
Drain Source voltage slope, $V_{DS} \leq 480\text{ V}$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55...+175	$^\circ\text{C}$

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	4.85	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Maximum)	R_{thJA}	62	$^{\circ}\text{C}/\text{W}$

Table 3. Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	500			V
Zero Gate Voltage Drain Current($T_c=25^{\circ}\text{C}$)	I_{DSS}	$V_{DS}=500V, V_{GS}=0V$			1	μA
Zero Gate Voltage Drain Current($T_c=125^{\circ}\text{C}$)	I_{DSS}	$V_{DS}=500V, V_{GS}=0V$			50	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 200	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	3		4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=3.5A$		470	540	m Ω
Dynamic Characteristics						
Gate Resistance	R_g	$F=1\text{MHz}, \text{D-S short}$		60		Ω
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V,$ $F=1\text{MHz}$		466		pF
Output Capacitance	C_{oss}			55		pF
Reverse Transfer Capacitance	C_{riss}			4.7		pF
Total Gate Charge	Q_g	$V_{DS}=380V, I_D=3.5A,$ $V_{GS}=10V$		13.3	15	nC
Gate-Source Charge	Q_{gs}			4.4		nC
Gate-Drain Charge	Q_{gd}			4.3		nC
Gate plateau voltage	V_{gp}			5.5		V
Switching times						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=380V, I_D=4A,$ $R_G=4\Omega, V_{GS}=10V$		8		nS
Turn-on Rise Time	t_r			10		nS
Turn-Off Delay Time	$t_{d(off)}$			41		nS
Turn-Off Fall Time	t_f			9		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I_{SD}	$T_c=25^{\circ}\text{C}$			7.5	A
Pulsed-Source-drain current(Body Diode)	I_{SDM}				22.5	A
Forward on voltage	V_{SD}	$T_J=25^{\circ}\text{C}, I_{SD}=7.5A, V_{GS}=0V$		1.0	1.2	V
Reverse Recovery Time	t_{rr}	$T_J=25^{\circ}\text{C}, I_F=3.5A,$ $di/dt=100A/\mu s$		185		nS
Reverse Recovery Charge	Q_{rr}			1.5		μC
Peak reverse recovery current	I_{rrm}			12		A

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

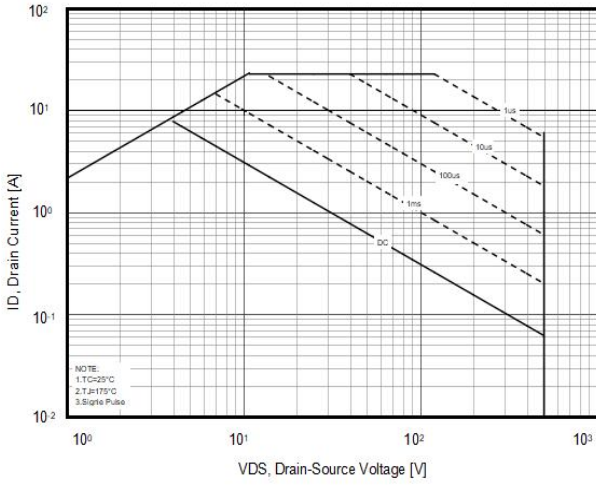


Figure2. Source-Drain Diode Forward Voltage

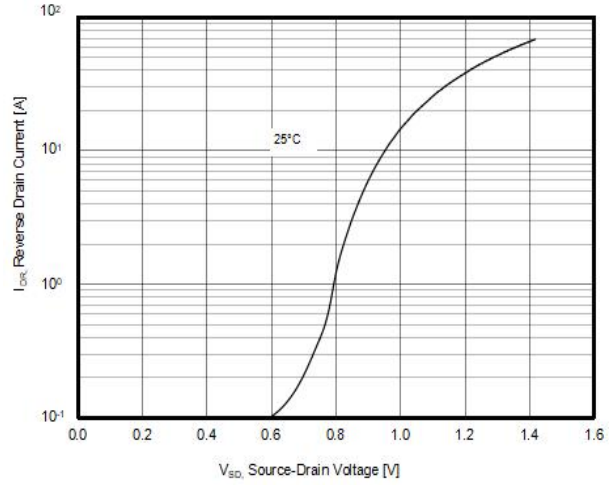


Figure3. Output characteristics

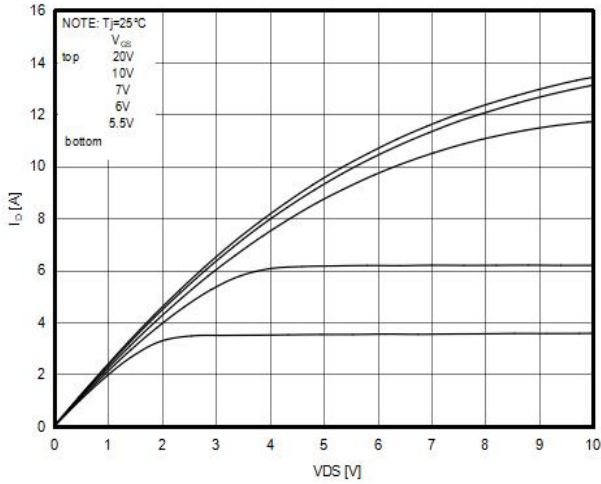


Figure4. Transfer characteristics

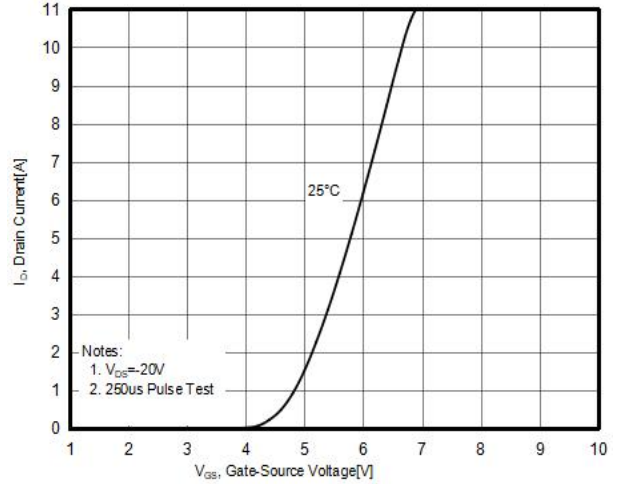


Figure5. Static drain-source on resistance

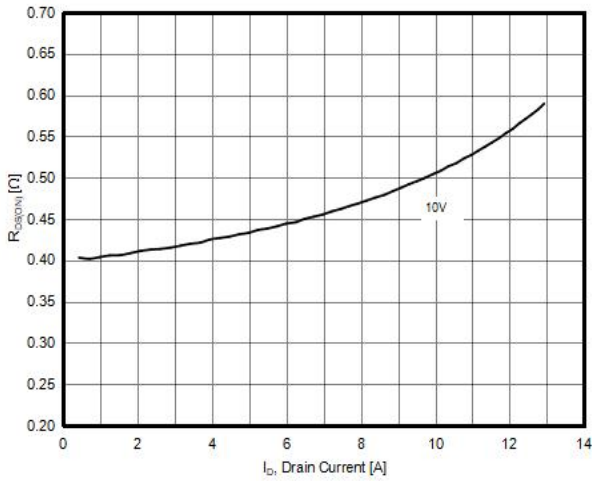


Figure6. R_DS(ON) vs Junction Temperature

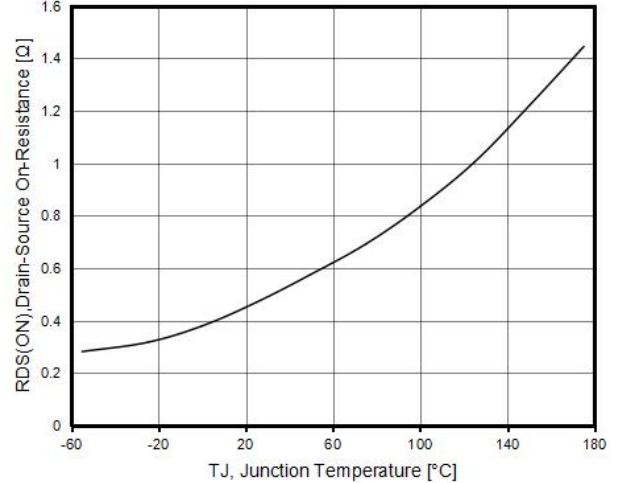


Figure7. BV_{DSS} vs Junction Temperature

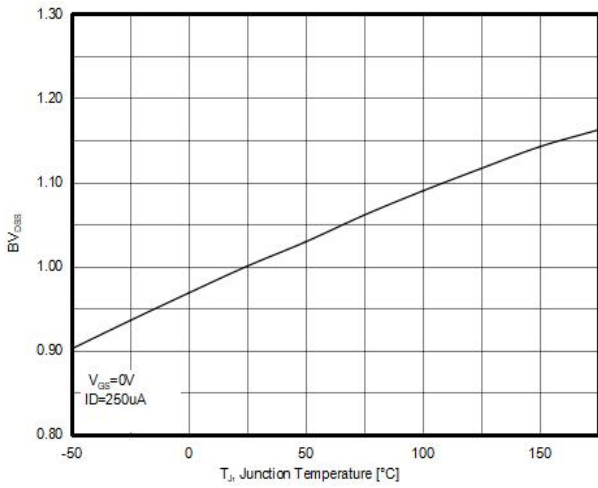


Figure8. Maximum I_D vs Junction Temperature

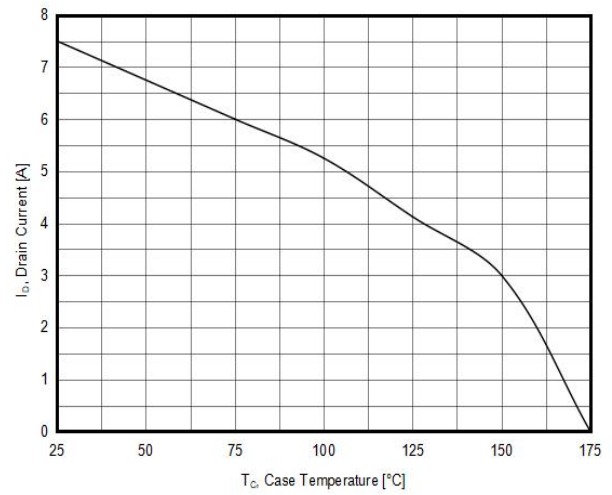


Figure9. Gate charge waveforms

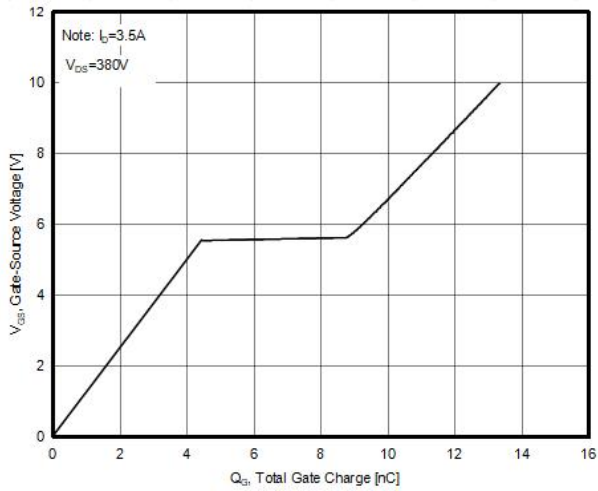
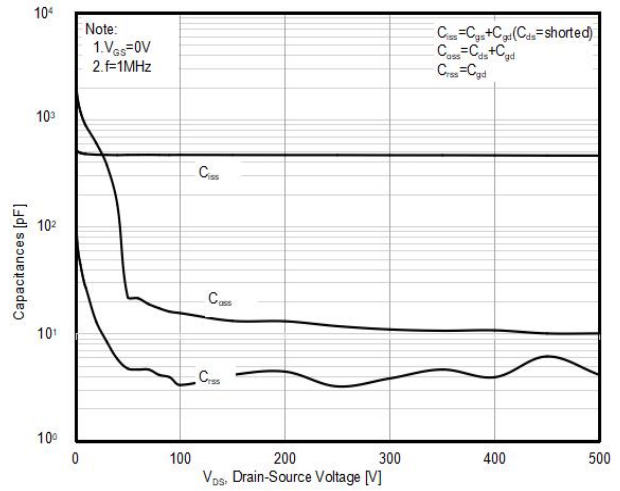


Figure10. Capacitance

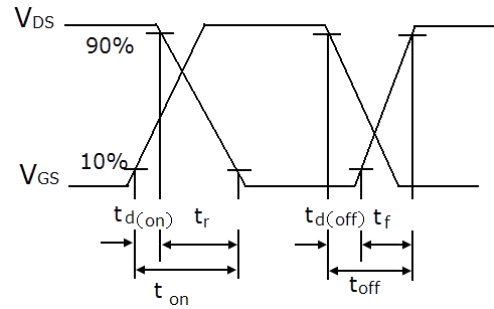


Test circuit

1) Gate charge test circuit & Waveform



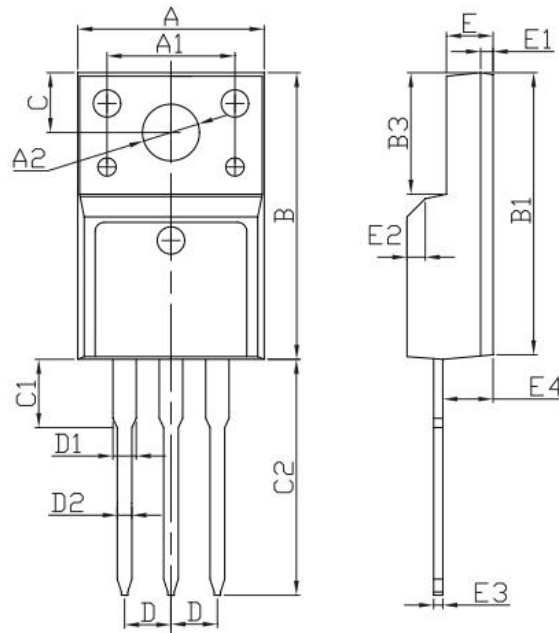
2) Switch Time Test Circuit:



3) Unclamped Inductive Switching Test Circuit & Waveforms

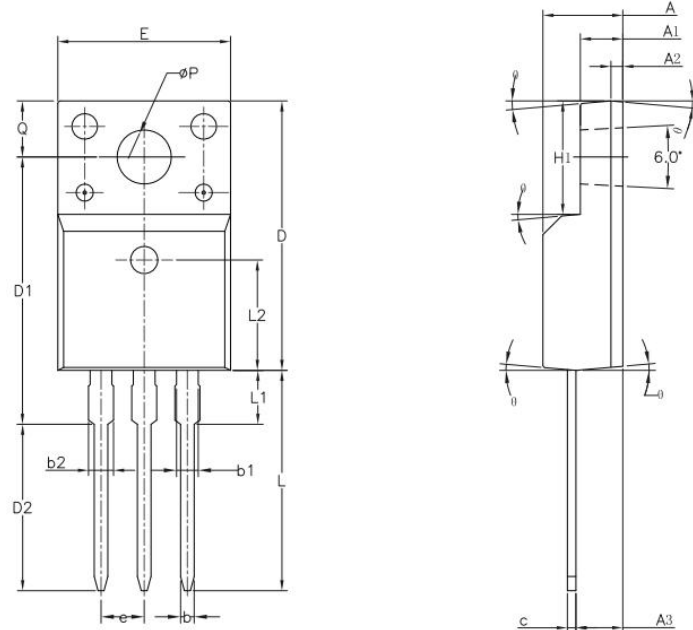


TO-220F-3L-L Package Information



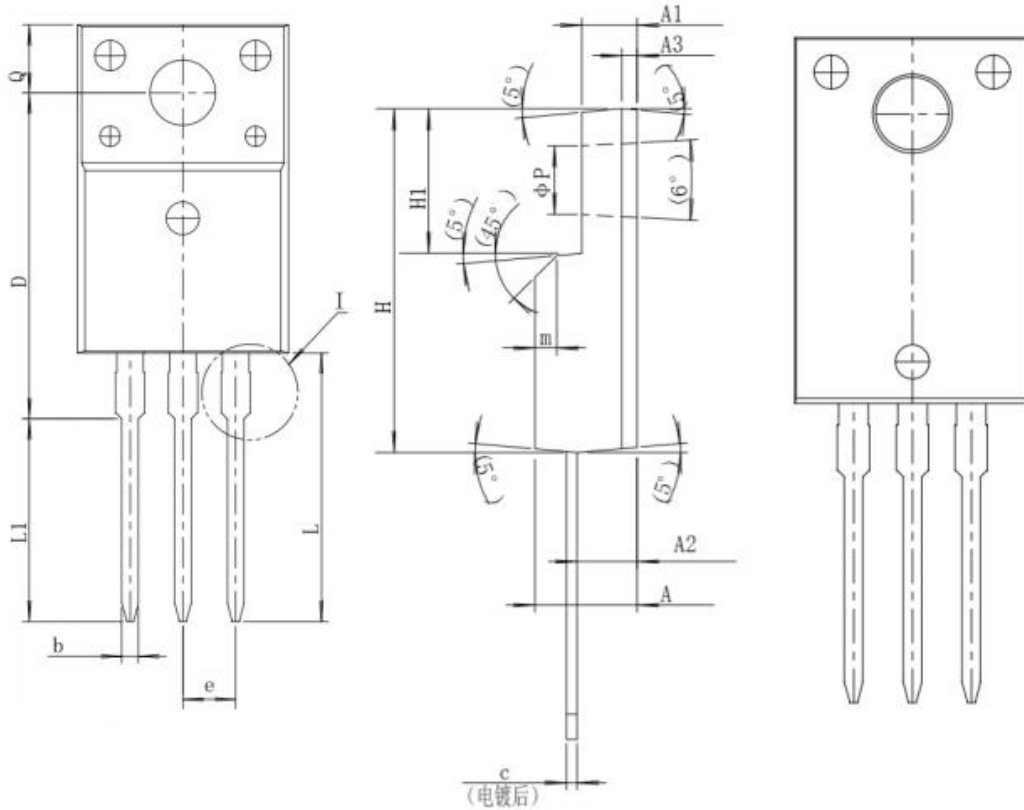
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.86	10.46	0.387	0.411
A1	6.80	7.20	0.267	0.283
A2	2.92	3.32	0.115	0.130
A3	9.40	10.00	0.369	0.393
B	15.40	16.40	0.605	0.644
B1	15.10	16.10	0.593	0.633
B2	4.40	5.00	0.173	0.196
B3	6.40	7.00	0.251	0.275
C	3.05	3.55	0.120	0.139
C1	2.95	3.55	0.116	0.139
C2	28.20	29.20	1.108	1.147
D	2.54 BSC		0.100 BSC	
D1	--	1.47	--	0.058
D2	0.60	1.00	0.024	0.039
E	2.30	2.80	0.090	0.110
E1	0.45	0.95	0.018	0.037
E2	45.0°		45.0°	
E3	0.30	0.70	0.012	0.028
E4	2.45	3.05	0.096	0.120

TO-220F-3L-P Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.50	4.83	0.177	0.190
A1	2.34	2.74	0.092	0.108
A2	0.70 REF		0.028 REF	
A3	2.56	2.93	0.101	0.115
b	0.70	0.90	0.028	0.035
b1	1.18	1.38	0.046	0.054
b2	--	1.47	--	0.058
c	0.45	0.60	0.018	0.024
D	15.67	16.07	0.616	0.631
D1	15.55	15.95	0.611	0.627
D2	9.60	10.00	0.377	0.393
E	9.96	10.36	0.391	0.407
e	2.54 BSC		0.100 BSC	
H1	6.48	6.88	0.255	0.270
L	12.68	13.28	0.498	0.522
L1	--	3.50	--	0.138
L2	6.50 REF		0.255 REF	
∅ P	3.08	3.28	0.121	0.129
Q	3.20	3.40	0.126	0.134
θ1	1.0°	5.0°	1.00°	5.00°

TO-220F-3L-M Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.60	4.80	0.181	0.189
A1	2.44	2.64	0.096	0.104
A2	2.65	2.85	0.104	0.112
A3	0.70 REF		0.028 REF	
b	0.70	0.90	0.028	0.035
b2	1.18	1.39	0.046	0.055
b1	1.28	1.47	--	0.058
c	0.45	0.60	0.018	0.024
D	15.64	15.85	0.614	0.623
E	10.06	10.26	0.395	0.403
e	2.54 BSC		0.100 BSC	
H	15.77	15.97	0.620	0.627
H1	6.58	6.78	0.259	0.266
L	12.68	13.28	0.498	0.522
L1	9.60	10.00	0.377	0.393
∅ P	3.08	3.28	0.121	0.129
Q	3.20	3.40	0.126	0.134

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